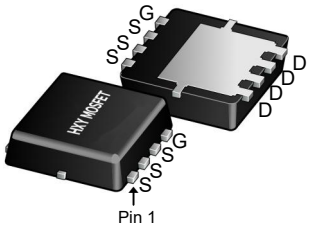
## Description

The HXY50P03DF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.




DFN3X3-8L

## General Features

$V_{DS}$ = -30V $I_D$ =-50 A

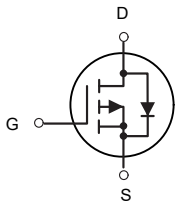
$R_{DS(ON)}$ < 13mΩ @ $V_{GS}$=-10V

## Application

Battery protection

Load switch

Uninterruptible power supply




P-Channel MOSFET

## Package Marking and Ordering Information

| Product ID | Pack | Marking | Qty(PCS) |
|---|---|---|---|
| HXY50P03DF | DFN3X3-8L | 50P03 XXX YYYY | 5000 |

## Absolute Maximum Ratings (TC=25℃ unless otherwise specified)

| Symbol | Parameter | Rating | | Units |
|---|---|---|---|---|
| | | 10s | Steady State | |
| VDS | Drain-Source Voltage | -30 | | V |
| VGS | Gate-Source Voltage | ±20 | | V |
| $I_D$@$T_C$=25℃ | Continuous Drain Current, $V_{GS}$ @ -10V[1] | -50 | | A |
| $I_D$@$T_C$=100℃ | Continuous Drain Current, $V_{GS}$ @ -10V[1] | -27 | | A |
| $I_D$@$T_A$=25℃ | Continuous Drain Current, $V_{GS}$ @ -10V[1] | -14.3 | -9 | A |
| $I_D$@$T_A$=70℃ | Continuous Drain Current, $V_{GS}$ @ -10V[1] | -11.4 | -7.2 | A |
| IDM | Pulsed Drain Current[2] | -130 | | A |
| EAS | Single Pulse Avalanche Energy[3] | 125 | | mJ |
| IAS | Avalanche Current | -50 | | A |
| $P_D$@$T_C$=25℃ | Total Power Dissipation[4] | 37 | | W |
| $P_D$@$T_A$=25℃ | Total Power Dissipation[4] | 4.2 | 1.67 | W |
| TSTG | Storage Temperature Range | -55 to 150 | | ℃ |
| $T_J$ | Operating Junction Temperature Range | -55 to 150 | | ℃ |

| | | | |
|---|---|---|---|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient [1] | 75 | ℃/W |
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient [1] (t ≤10s) | 30 | ℃/W |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case[1] | 3.36 | ℃/W |

**Electrical Characteristics ($T_J$=25 ℃, unless otherwise noted)**

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|
| $BV_{DSS}$ | Drain-Source Breakdown Voltage | $V_{GS}$=0V , $I_D$=-250uA | -30 | --- | --- | V |
| $\triangle BV_{DSS}/\triangle T_J$ | BVDSS Temperature Coefficient | Reference to 25℃ , $I_D$=-1mA | --- | -0.0232 | --- | V/℃ |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance[2] | $V_{GS}$=-10V , $I_D$=-30A | --- | 9 | 13 | mΩ |
| | | $V_{GS}$=-4.5V , $I_D$=-15A | --- | 16 | 22 | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}$=$V_{DS}$ , $I_D$ =-250uA | -1.2 | --- | -2.5 | V |
| $\triangle V_{GS(th)}$ | $V_{GS(th)}$ Temperature Coefficient | | --- | 4.6 | --- | mV/℃ |
| $I_{DSS}$ | Drain-Source Leakage Current | $V_{DS}$=-24V , $V_{GS}$=0V , $T_J$=25℃ | --- | --- | -1 | uA |
| | | $V_{DS}$=-24V , $V_{GS}$=0V , $T_J$=55℃ | --- | --- | -5 | |
| $I_{GSS}$ | Gate-Source Leakage Current | $V_{GS}$=±20V , $V_{DS}$=0V | --- | --- | ±100 | nA |
| gfs | Forward Transconductance | $V_{DS}$=-5V , $I_D$=-30A | --- | 30 | --- | S |
| $R_g$ | Gate Resistance | $V_{DS}$=0V , $V_{GS}$=0V , f=1MHz | --- | 9 | --- | Ω |
| $Q_g$ | Total Gate Charge (-4.5V) | $V_{DS}$=-15V , $V_{GS}$=-4.5V , $I_D$=-15A | --- | 22 | --- | nC |
| $Q_{gs}$ | Gate-Source Charge | | --- | 8.7 | --- | |
| $Q_{gd}$ | Gate-Drain Charge | | --- | 7.2 | --- | |
| $T_{d(on)}$ | Turn-On Delay Time | $V_{DD}$=-15V , $V_{GS}$=-10V , $R_G$=3.3 $I_D$=-15A | --- | 8 | --- | ns |
| $T_r$ | Rise Time | | --- | 73.7 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time | | --- | 61.8 | --- | |
| $T_f$ | Fall Time | | --- | 24.4 | --- | |
| $C_{iss}$ | Input Capacitance | $V_{DS}$=-15V , $V_{GS}$=0V , f=1MHz | --- | 2215 | --- | pF |
| $C_{oss}$ | Output Capacitance | | --- | 310 | --- | |
| $C_{rss}$ | Reverse Transfer Capacitance | | --- | 237 | --- | |
| $I_S$ | Continuous Source Current[1,5] | $V_G$=$V_D$=0V , Force Current | --- | --- | -42 | A |
| $I_{SM}$ | Pulsed Source Current[2,5] | | --- | --- | -130 | A |
| $V_{SD}$ | Diode Forward Voltage[2] | $V_{GS}$=0V , $I_S$=-1A , $T_J$=25℃ | --- | --- | -1 | V |
| $t_{rr}$ | Reverse Recovery Time | $I_F$=-15A , dI/dt=100A/μs , $T_J$=25℃ | --- | 19 | --- | nS |
| $Q_{rr}$ | Reverse Recovery Charge | | --- | 9 | --- | nC |

Note :

1.The data tested by surface mounted on a 1 inch$^2$ FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width ≦ 300us duty cycle≦2%

3.The EAS data shows Max. rating . The test condition is $V_{DD}$ =-25V $V_{GS}$ =-10V,L=0.1mH,$I_{AS}$=-50A,

4.The power dissipation is limited by 150℃ junction temperature

5.The data is theoretically the same as $I_D$ and $I_{DM}$ , in real applications , should be limited by total power dissipation.

## Typical Characteristics

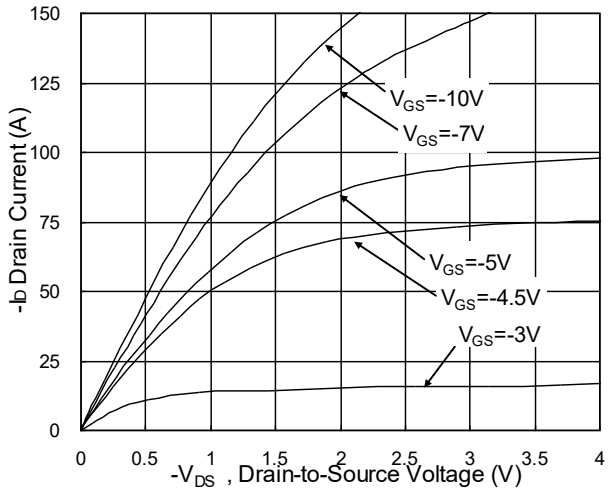



**Fig.1 Typical Output Characteristics**

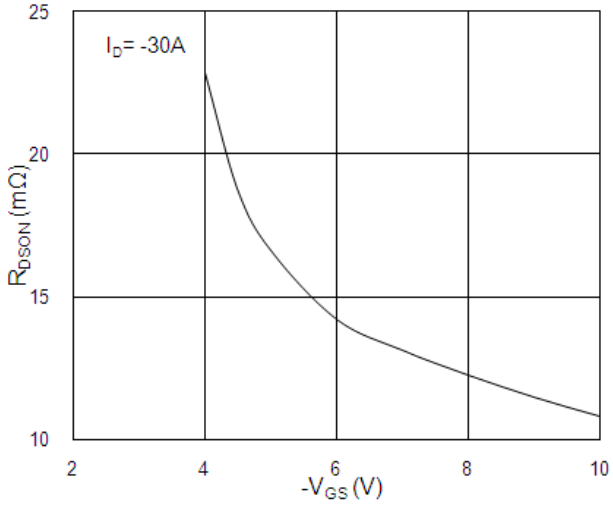



**Fig.2 On-Resistance vs. G-S Voltage**

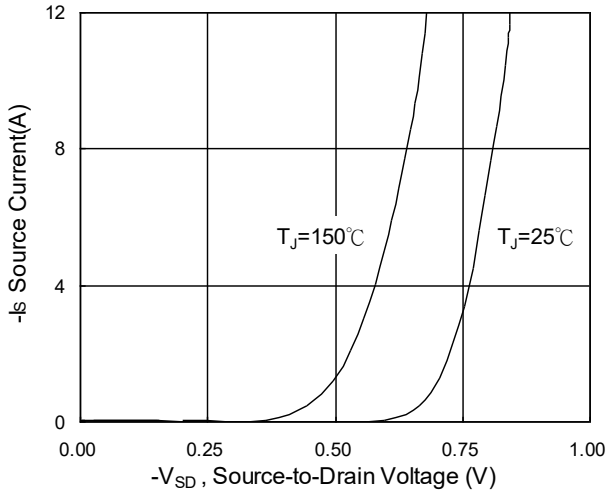



**Fig.3 Forward Characteristics of Reverse**

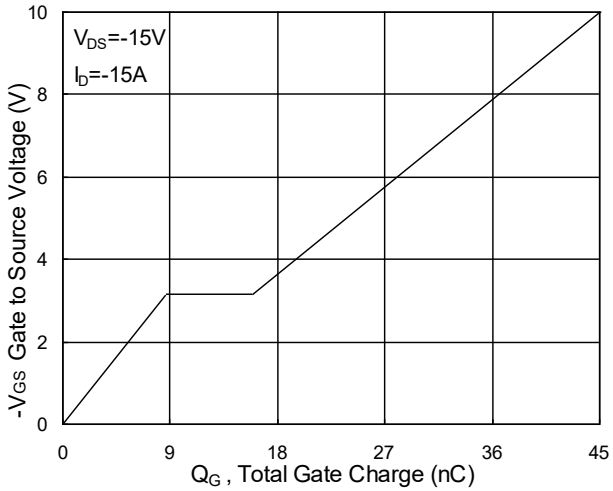



**Fig.4 Gate-Charge Characteristics**

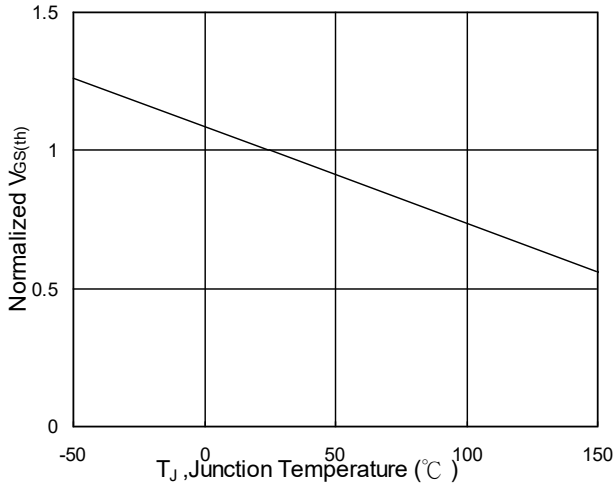



Fig.5 Normalized $V_{GS(th)}$ vs. $T_J$

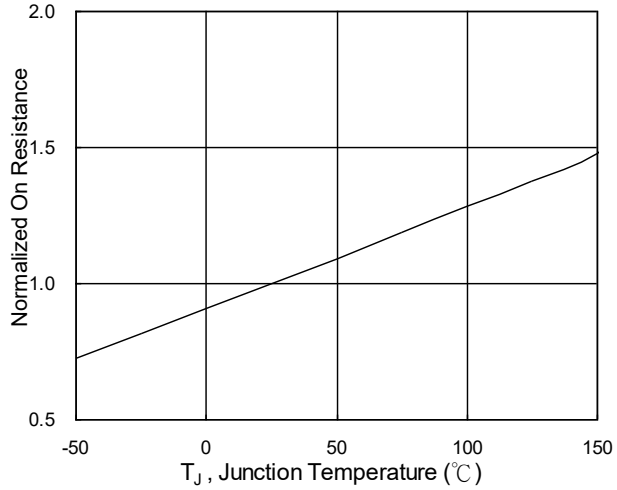



**Fig.6 Normalized $R_{DSON}$ vs. $T_J$**

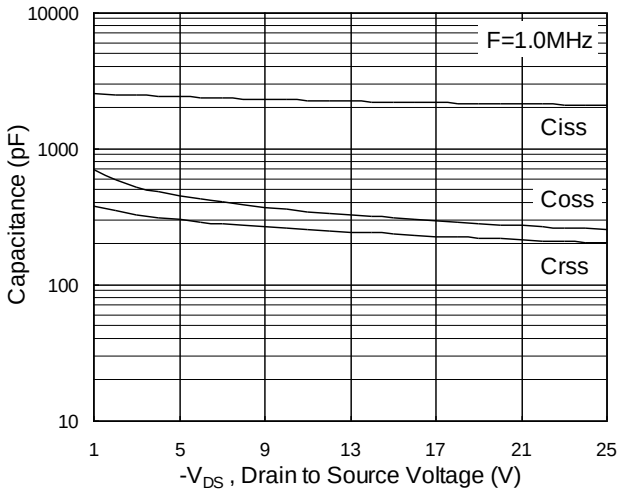



**Fig.7 Capacitance**

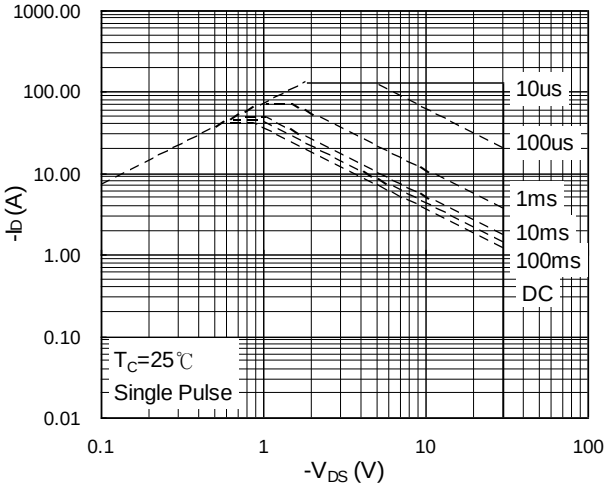



**Fig.8 Safe Operating Area**

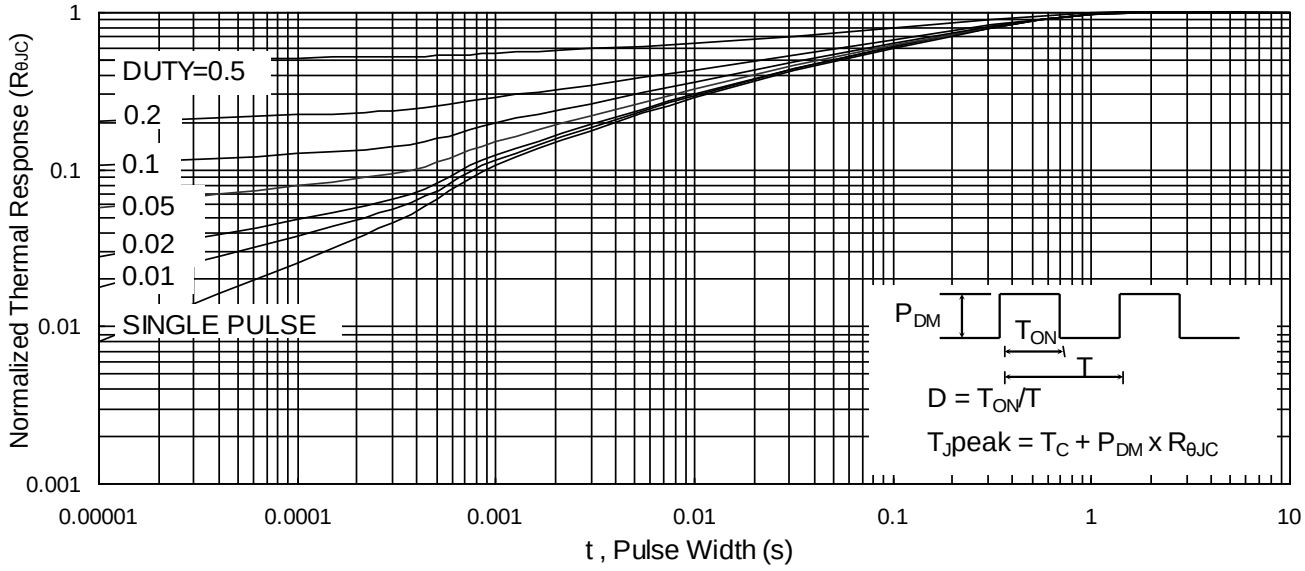



**Fig.9 Normalized Maximum Transient Thermal Impedance**

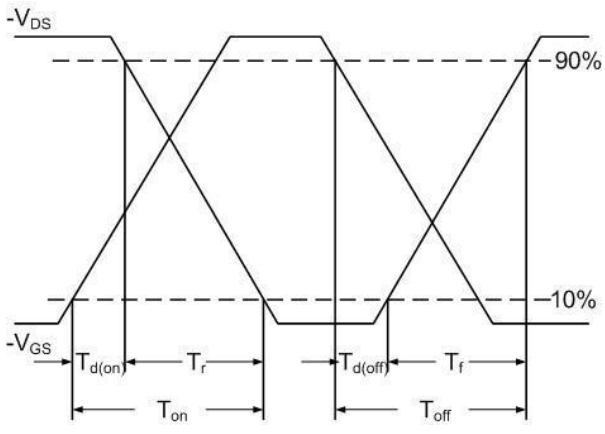



**Fig.10 Switching Time Waveform**

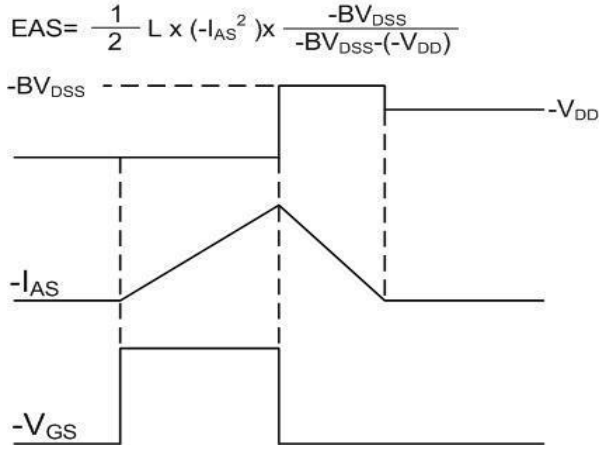
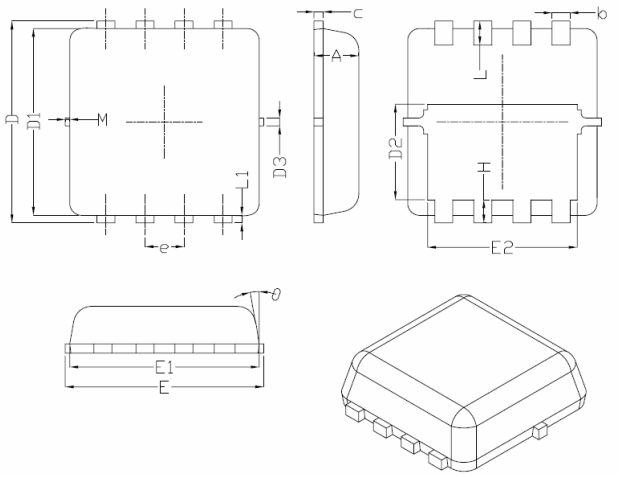



**Fig.11 Unclamped Inductive Switching Waveform**

## DFN3X3-8L Package Information




| Symbol | Dimensions In Millimeters | | |
|---|---|---|---|
| | Min. | Nom. | Max. |
| A | 0.70 | 0.75 | 0.80 |
| b | 0.25 | 0.30 | 0.35 |
| c | 0.10 | 0.15 | 0.25 |
| D | 3.25 | 3.35 | 3.45 |
| D1 | 3.00 | 3.10 | 3.20 |
| D2 | 1.48 | 1.58 | 1.68 |
| D3 | - | 0.13 | - |
| E | 3.20 | 3.30 | 3.40 |
| E1 | 3.00 | 3.15 | 3.20 |
| E2 | 2.39 | 2.49 | 2.59 |
| e | 0.65BSC | | |
| H | 0.30 | 0.39 | 0.50 |
| L | 0.30 | 0.40 | 0.50 |
| L1 | - | 0.13 | - |
| M | * | * | 0.15 |
| θ | | 10° | 12° |

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